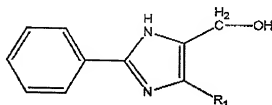


Abstract of the Disclosure

A paste for filling a throughhole, comprises: an epoxy resin; a curing agent; and a metal filler, wherein the metal filler is a powder comprising a base metal, and the curing agent
5 is an imidazole compound represented by the following formula (1):



(1)

wherein R₁ represents a hydrogen atom, an alkyl group having
10 1 to 10 carbon atoms, a hydroxyalkyl group having 1 to 10 carbon atoms or an alkyloxy group having 1 to 10 carbon atoms.